

## Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$ $T_A = +25^\circ\text{C}$
60V	80m $\Omega$ @ $V_{GS}=10\text{V}$	3.5A
	150m $\Omega$ @ $V_{GS}=4.5\text{V}$	2.5A

## Description

This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

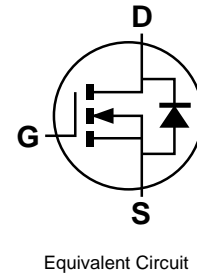
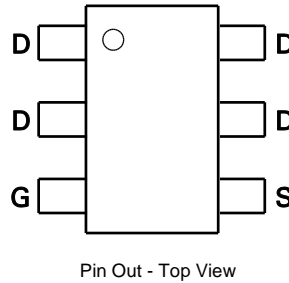
- DC-DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control

## Features and Benefits

- Low On-Resistance
- Fast Switching Speed
- Low Gate Drive
- Low Threshold
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

## Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208  $\text{\textcircled{3}}$
- Weight: 0.018 grams (Approximate)

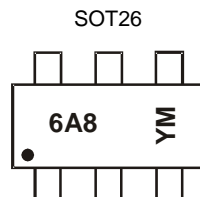


## Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
ZXMN6A08E6TA	Standard	SOT26	3,000 / Tape & Reel
ZXMN6A08E6TC	Standard	SOT26	10,000 / Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

## Marking Information



6A8 = Product Type Marking Code  
 YM = Date Code Marking  
 Y or  $\bar{Y}$  = Year (ex: C = 2015)  
 M or  $\bar{M}$  = Month (ex: 9 = September)

### Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022
Code	C	D	E	F	G	H	I	J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

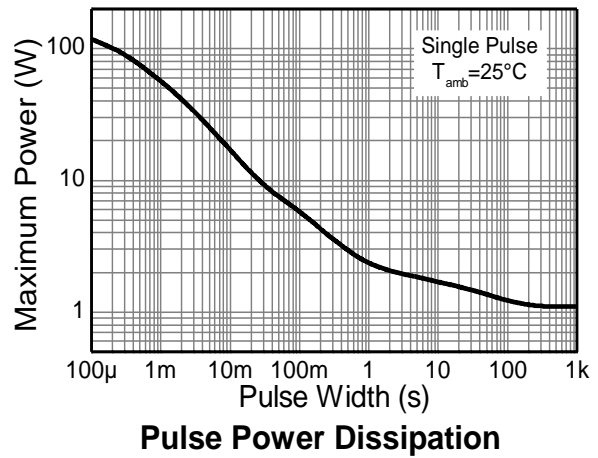
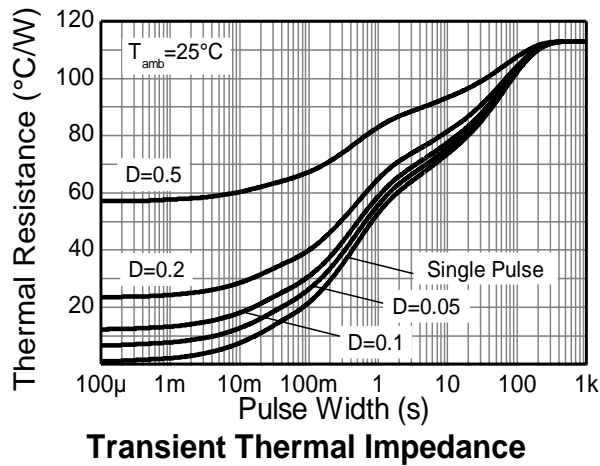
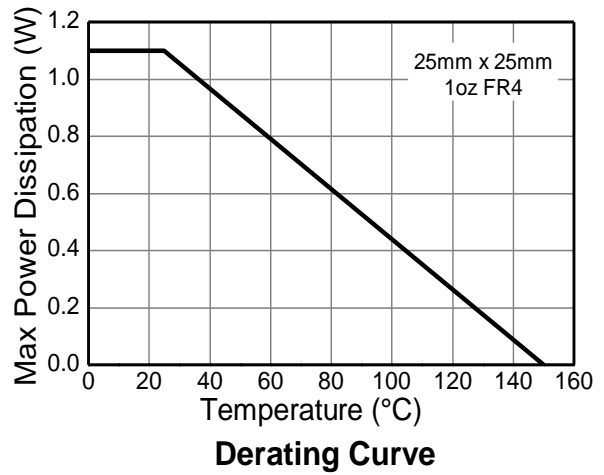
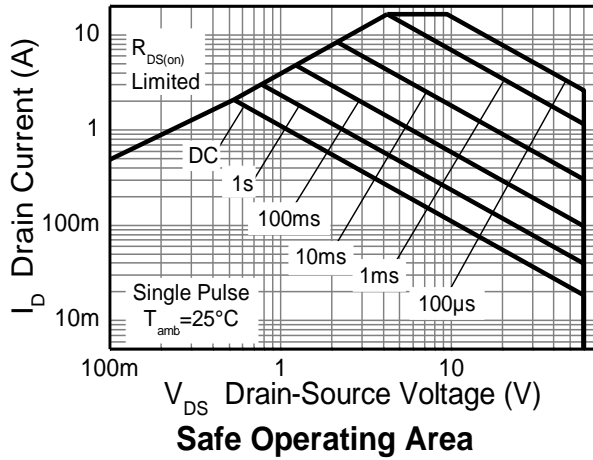
Characteristic			Symbol	Value	Unit	
Drain-Source Voltage			$V_{DSS}$	60	V	
Gate-Source Voltage			$V_{GS}$	$\pm 20$	V	
Continuous Drain Current	$V_{GS} = 10\text{V}$	(Note 6)	$I_D$	3.5	A	
		$T_A = +70^\circ\text{C}$ (Note 6)		2.8		
		(Note 5)		2.8		
Pulsed Drain Current	$V_{GS} = 10\text{V}$	(Note 7)	$I_{DM}$	16	A	
Continuous Source Current (Body Diode)			(Note 6)	$I_S$	2.6	A
Pulsed Source Current (Body Diode)			(Note 7)	$I_{SM}$	16	A

**Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 5)	$P_D$	1.1	W mW/ $^\circ\text{C}$
			8.8	
	(Note 6)		1.7 13.6	
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{\theta JA}$	113	$^\circ\text{C/W}$
	(Note 6)		73	
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

- Notes:
5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  6. Same as Note 5, except the device is measured at  $t \leq 10$  sec.
  7. Same as Note 5, except the device is pulsed with  $D = 0.02$  and pulse width 300 $\mu\text{s}$ . The pulse current is limited by the maximum junction temperature.

**Thermal Characteristics**

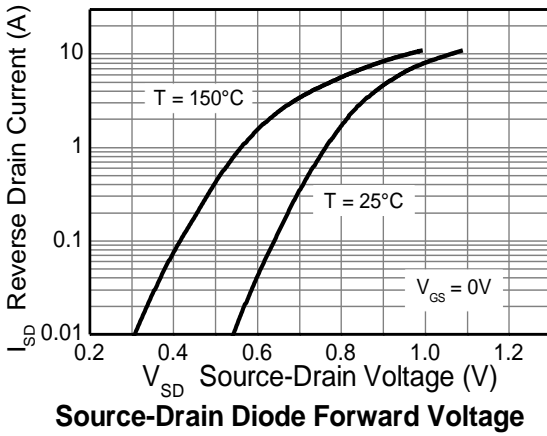
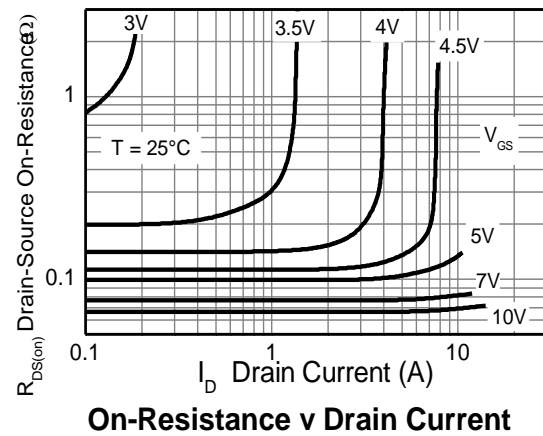
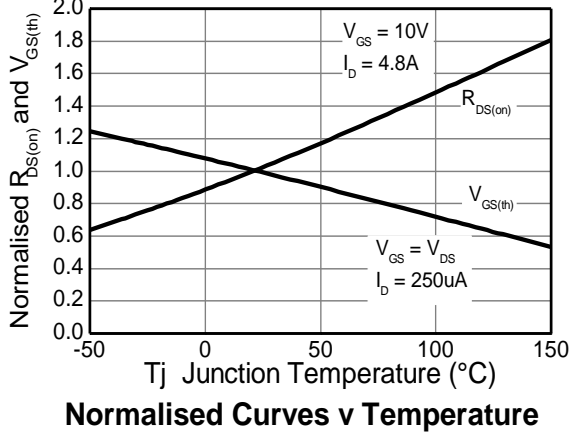
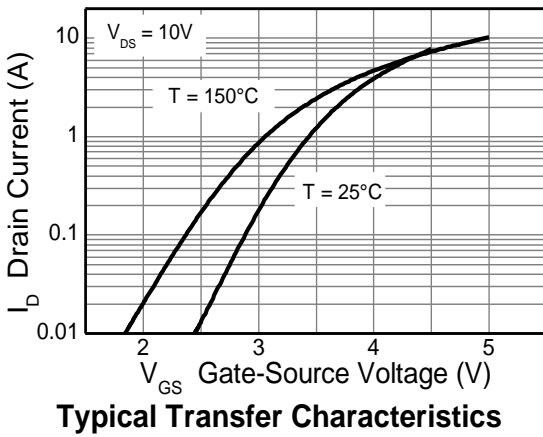
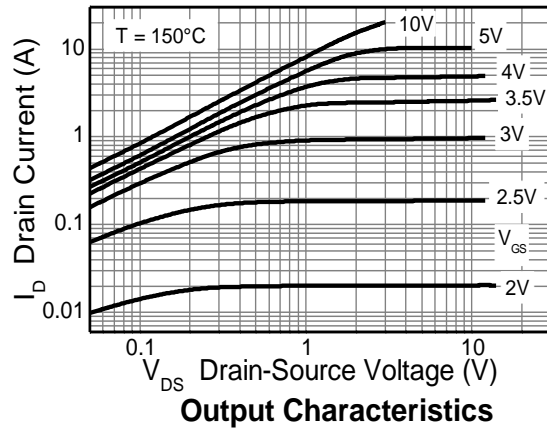
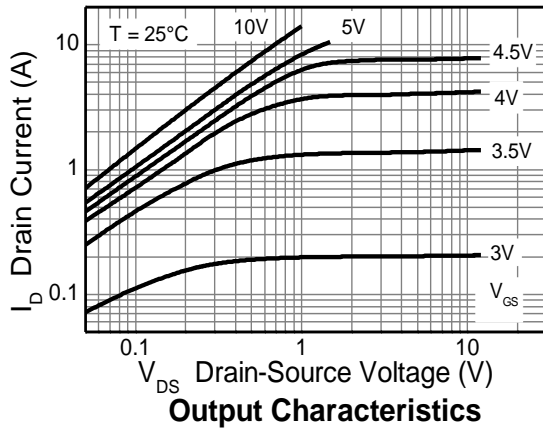


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

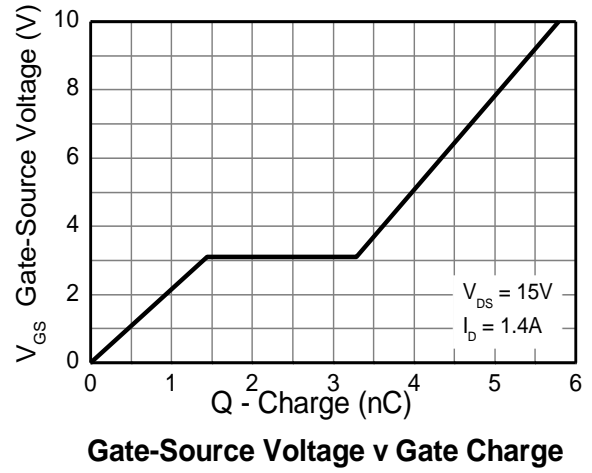
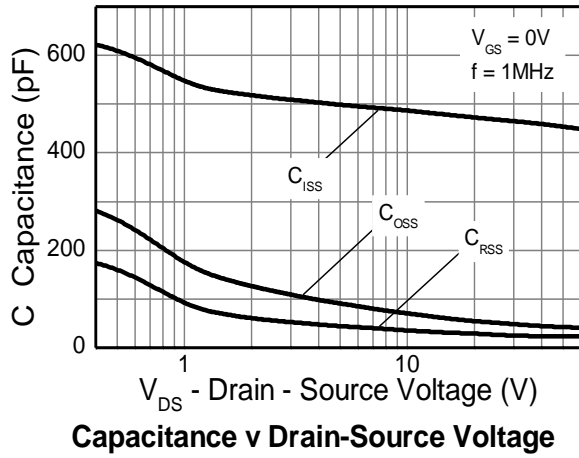
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	0.5	μA	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	—	—	V	I <sub>D</sub> = 250μA, V <sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 8)	R <sub>DS(on)</sub>	—	0.067	0.080	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.8A
			0.100	0.150		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4.2A
Forward Transconductance (Notes 8 & 9)	g <sub>fs</sub>	—	6.6	—	S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 4.8A
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	—	0.88	1.2	V	I <sub>S</sub> = 4A, V <sub>GS</sub> = 0V, T <sub>J</sub> = +25°C
Reverse Recovery Time (Note 9)	t <sub>rr</sub>	—	19.2	—	ns	I <sub>F</sub> = 1.4A, di/dt = 100A/μs,
Reverse Recovery Charge (Note 9)	Q <sub>rr</sub>	—	30.3	—	nC	T <sub>J</sub> = +25°C
<b>DYNAMIC CHARACTERISTICS (Note 9)</b>						
Input Capacitance	C <sub>iss</sub>	—	459	—	pF	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	44.2	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	24.1	—	pF	
Total Gate Charge (Note 10)	Q <sub>g</sub>	—	3.7	—	nC	V <sub>GS</sub> = 4.5V
Total Gate Charge (Note 10)	Q <sub>g</sub>	—	5.8	—	nC	V <sub>GS</sub> = 10V V <sub>DS</sub> = 30V I <sub>D</sub> = 1.4A
Gate-Source Charge (Note 10)	Q <sub>gs</sub>	—	1.4	—	nC	
Gate-Drain Charge (Note 10)	Q <sub>gd</sub>	—	1.9	—	nC	
Turn-On Delay Time (Note 10)	t <sub>D(on)</sub>	—	2.6	—	ns	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V I <sub>D</sub> = 1.5A, R <sub>G</sub> ≅ 6.0Ω
Turn-On Rise Time (Note 10)	t <sub>r</sub>	—	2.1	—	ns	
Turn-Off Delay Time (Note 10)	t <sub>D(off)</sub>	—	12.3	—	ns	
Turn-Off Fall Time (Note 10)	t <sub>f</sub>	—	4.6	—	ns	

- Notes:
8. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
  9. For design aid only, not subject to production testing.
  10. Switching characteristics are independent of operating junction temperatures.

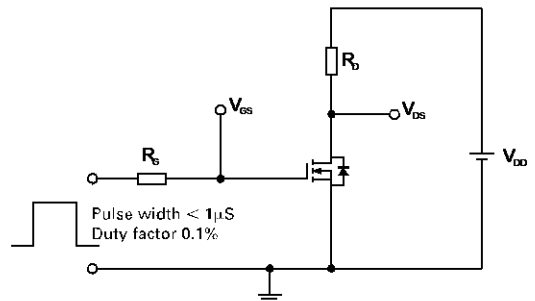
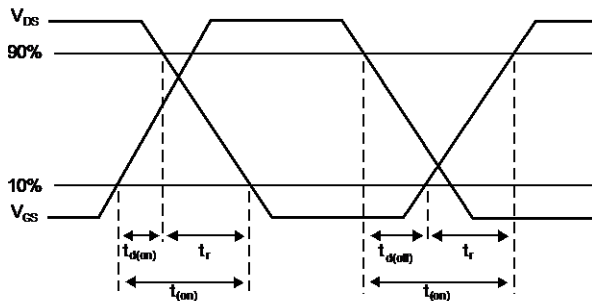
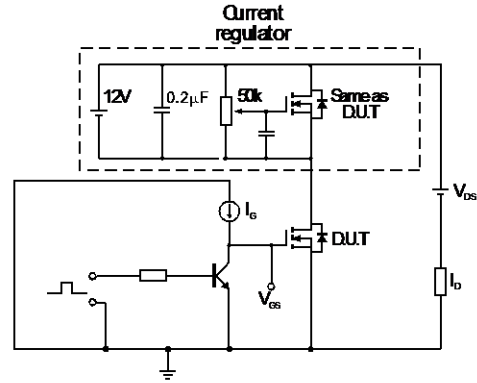
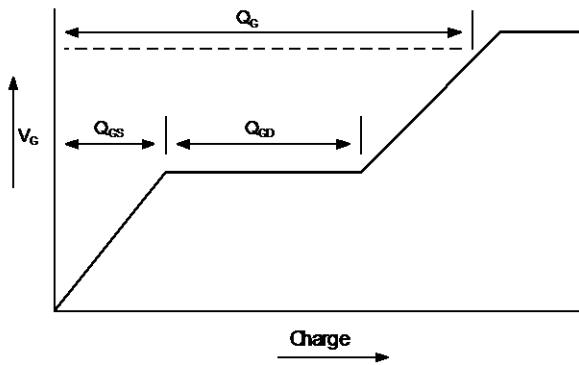
**Typical Characteristics**



**Typical Characteristics (cont.)**

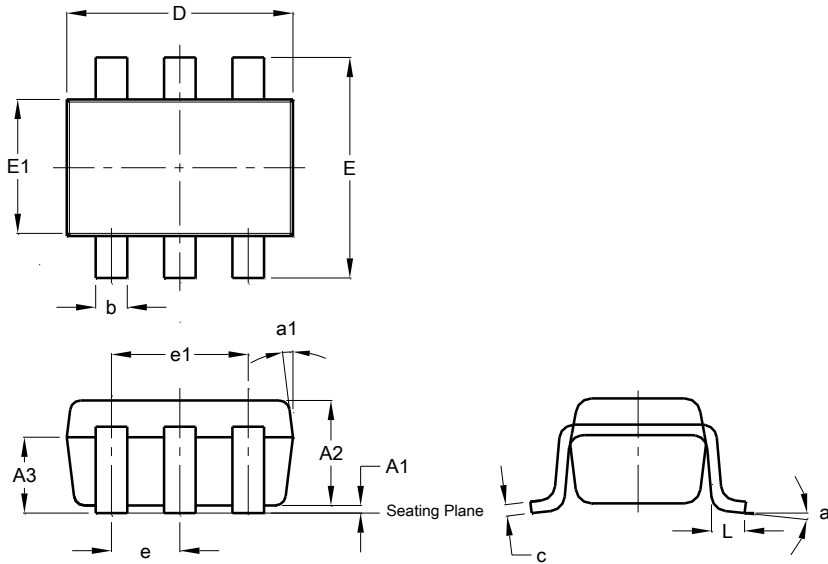


**Test Circuits**



## Package Outline Dimensions

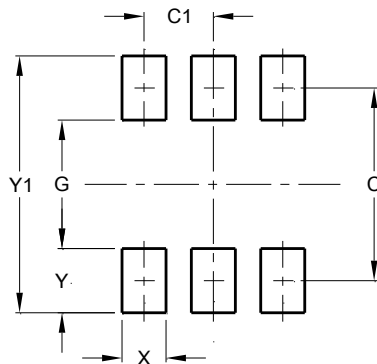
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20

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